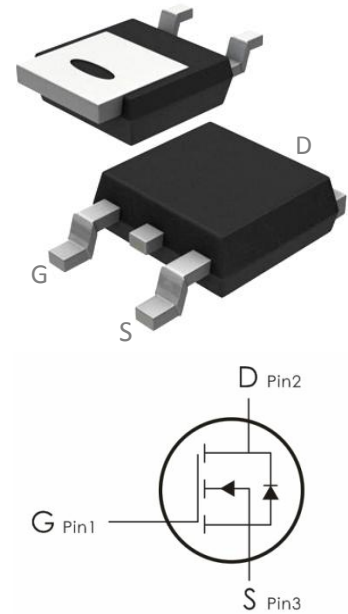


## Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.

## Features:

- 1)  $V_{DS}=40V, I_D=30A, R_{DS(ON)}<20m\ \Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_C=25^\circ C$	30	A
	Continuous Drain Current- $T_C=100^\circ C$	21	
	Continuous Drain Current- $T_A=25^\circ C$	8.4	
	Continuous Drain Current- $T_A=70^\circ C$	6.7	
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	80	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>3</sup>	31.3	mJ
$I_{AS}$	Avalanche Current	25	A
$P_D$	Power Dissipation <sup>4</sup> - $T_C=25^\circ C$	31.3	W
	Power Dissipation <sup>4</sup> - $T_A=25^\circ C$	2	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

**Thermal Characteristics:**

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case <sup>1</sup>	4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient <sup>1</sup>	62	

**Electrical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

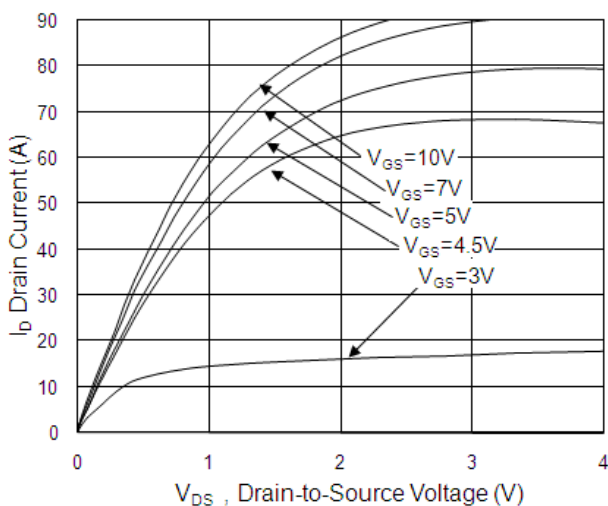
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	40	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=32V, T_J = 25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{GS}=0V, V_{DS}=32V, T_J = 55^\circ\text{C}$	---	---	5	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1	---	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance <sup>2</sup>	$V_{GS}=10V, I_D=15A$	---	---	20	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	---	25	m $\Omega$
$G_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=15A$	---	34	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.1	---	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1010	---	pF
$C_{oss}$	Output Capacitance		---	102	---	
$C_{rss}$	Reverse Transfer Capacitance		---	70	---	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=20V, I_D=15A, R_G=3.3\Omega,$	---	2.8	---	ns
$t_r$	Rise Time	$V_{GS}=10V$	---	12.8	---	ns

<b>t<sub>d(off)</sub></b>	Turn-Off Delay Time	$V_{DD}=20V, I_D=15A, R_G=3.3\Omega,$ $V_{GS}=10V$	---	21.2	---	ns
<b>t<sub>f</sub></b>	Fall Time		---	6.4	---	ns
<b>Q<sub>g</sub></b>	Total Gate Charge	$V_{DS}=32V, V_{GS}=4.5V, I_D=15A$	---	10	---	nC
<b>Q<sub>gs</sub></b>	Gate-Source Charge		---	2.55	---	nC
<b>Q<sub>gd</sub></b>	Gate-Drain Charge		---	4.8	---	nC
<b>Drain-Source Diode Characteristics</b>						
<b>V<sub>SD</sub></b>	Source-Drain Diode Forward Voltage <sup>2</sup>	$I_S=1A, V_{GS}=0V, T_J=25^\circ C$	---	---	1.2	V
<b>I<sub>S</sub></b>	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V, \text{ Force Current}$	---	---	33	A
<b>I<sub>SM</sub></b>	Pulsed Source Current <sup>2,5</sup>		---	---	80	A
<b>T<sub>rr</sub></b>	Reverse Recovery Time	$I_F=15A, dI/dt=100A/\mu s$	---	10	---	ns
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge	$T_J=25^\circ C$	---	3.1	---	nC

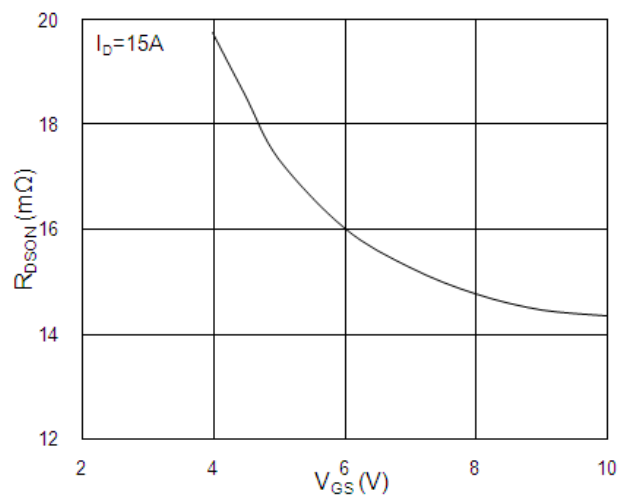
## Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=25A$
- 4.The power dissipation is limited by 150<sup>o</sup>C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

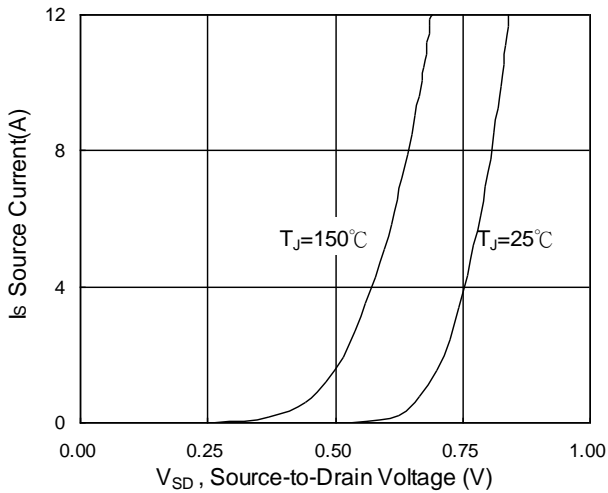
## Typical Characteristics: (T<sub>J</sub>=25<sup>o</sup>C unless otherwise noted)



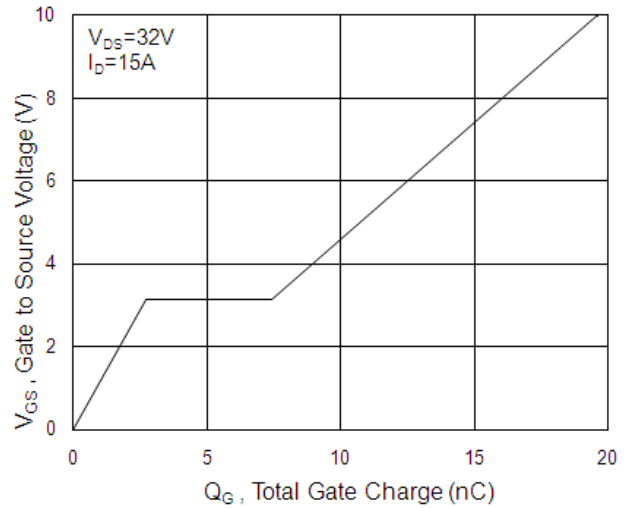
**Fig.1 Typical Output Characteristics**



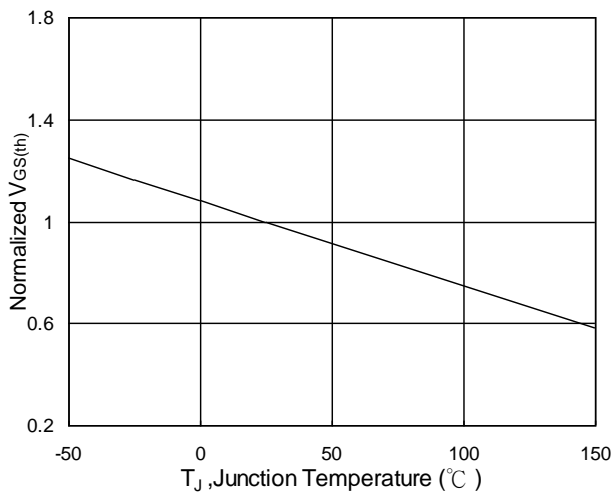
**Fig.2 On-Resistance vs. G-S Voltage**



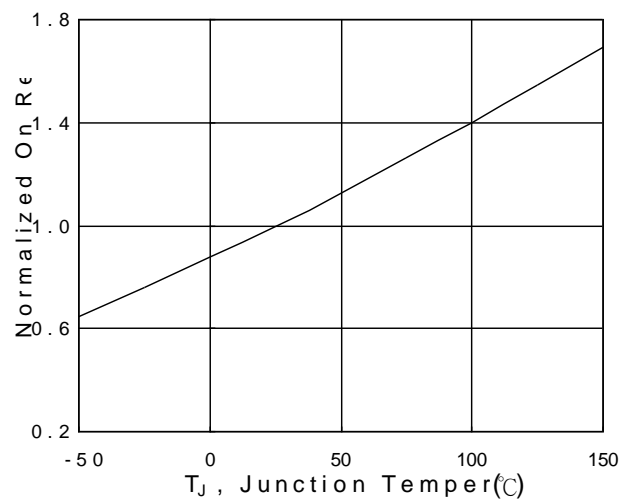
**Fig.3 Forward Characteristics Of Reverse**



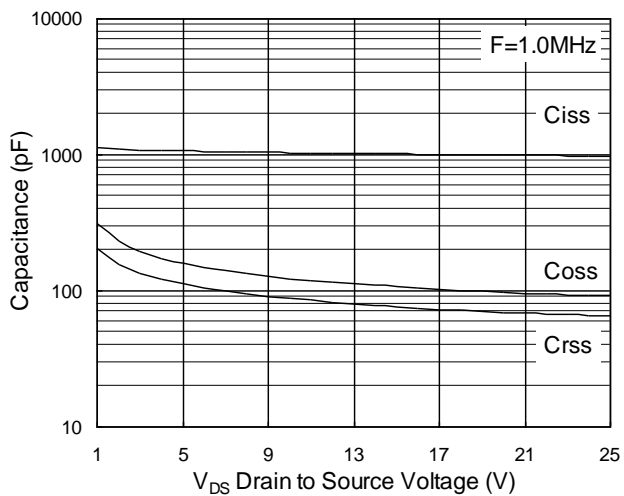
**Fig.4 Gate-Charge Characteristics**



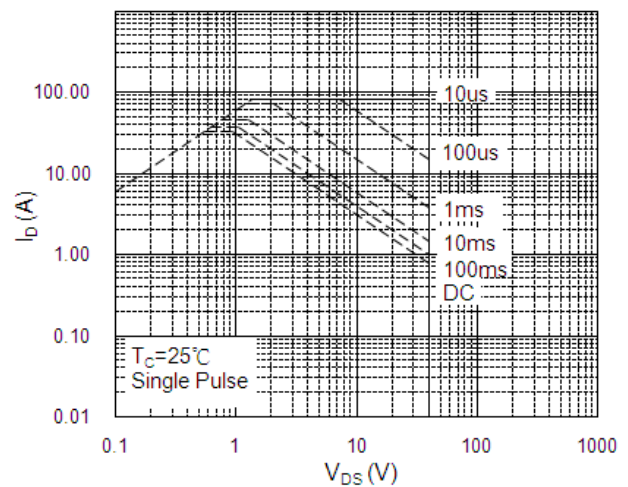
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



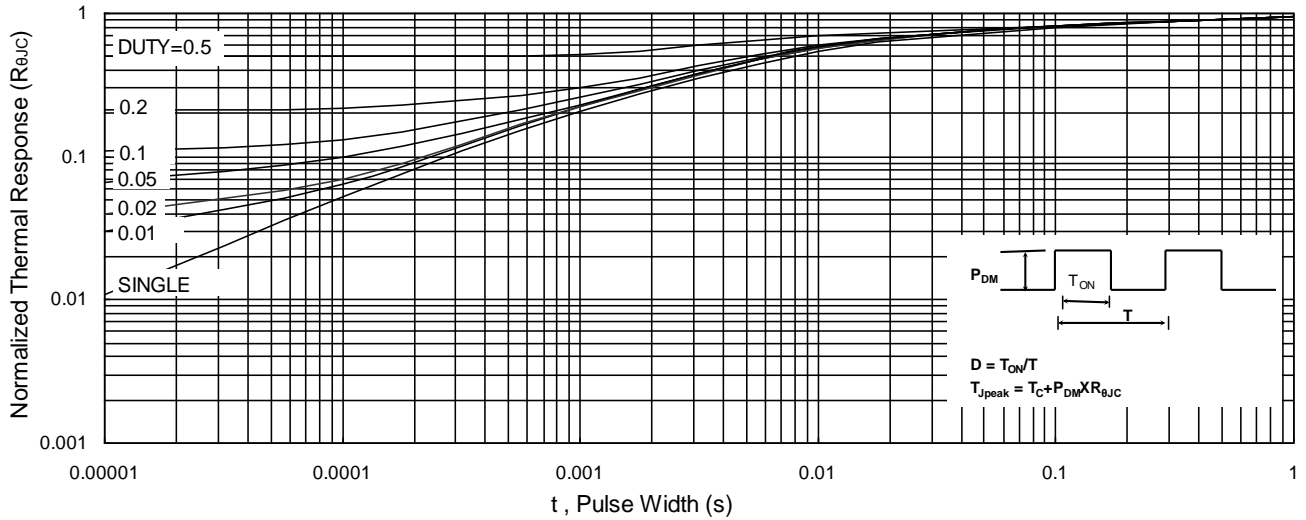
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



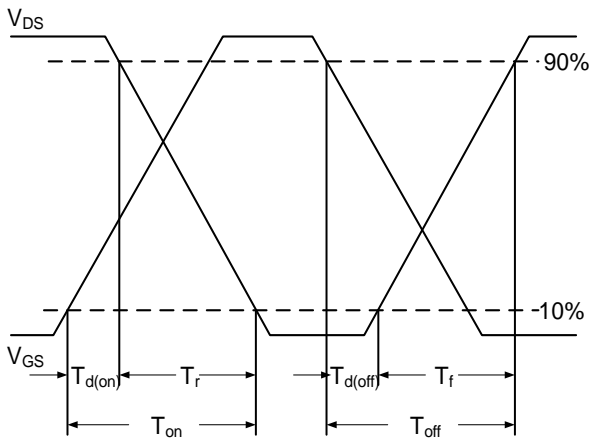
**Fig.7 Capacitance**



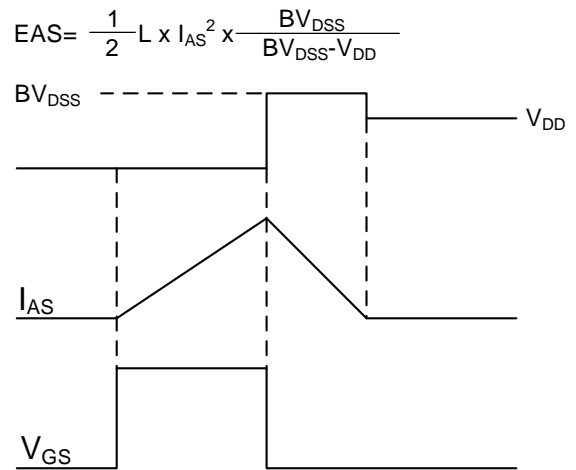
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**



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